



## Automatic Large Area Bond Tester 8600C

### Bond System

**Testheads** Pullheads – 100cN, 1000cN, 5000cN  
Shearheads – 500cN, 5000cN

### Machine Base

#### Mechanics

**Table travel** axis travel: approx.: x= 720 mm y=512 mm  
**X, Y, Z** Resolution 1 µm, repeatability 5 µm  
**Speed** All axes programmable from 0.2 to 16 mm/s  
Test speed from 0.2 to 5mm/s

#### Measurement heads

**Accuracy** 0.25% of maximum value  
**Calibration** Stored in measurement head, temperature-Compensated load cell  
Optional calibration at customers side (specific tools)

#### Control

**Computer** Dual Core PC, Ethernet, USB 2.0/3.0  
GigE-CCD-Colour Camera,  
fully networkable in TCP/IP server

**Monitor** TFT flat screen monitor 22"

**Operating system** Windows 10

**Printer** all Windows-compatible printers can be installed

### 8600C:

The automatic large area bond tester 8600C complements F&S Bondtec Semiconductor GmbH die- and wire- bonders.

The PC controlled moving axis allows any number of bonds to be tested automatically from a stored program on a large area (eg. for Battery-, Solar-application,..).

Results can be analysed and output immediately or exported in a number of data base formats for subsequent analysis as desired.

Powerful extended capabilities enable measurements such as force/time curves to be made and deliver more data about the quality of the bond tested.

Exchangeable measurement cartridges ensure rapid conversion to different force ranges. The calibration curves of all measurement cartridges are stored internally; additional heads for shear, and tweezer testing with customer-specific tools and jaws are available.

After a first programming a reproducible pull- or shear-test can be guaranteed for all following components.

## Additional features

<b>Programming</b>	Automatic repeat measurements on hybrids or COB using the programmable head movement and Pattern Recognition Unit (PRU)
<b>Evaluation</b>	Statistics such as mean value, standard deviation, trend, cpk, etc. Based on SQL Databank
<b>Export format</b>	SQL, CSV, HTML
<b>Other</b>	Operator profile, various password levels, optional barcode readers for product Identification; feedback of measured values to die and wire bonders for parameter optimisation optional

## General

<b>Microscope</b>	Stereoscope Olympus, other microscopes optional
<b>Lighting</b>	LED spot light
<b>Dimensions</b>	approx. height 200cm, width 130cm, depth 100cm, approx. 700kg
<b>Supplies</b>	230 VAC,
<b>Connections</b>	Air 6 bar; vacuum 0,7 bar

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